



SOD123 Diodes

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 26.42%	Iron (Fe)	7439-89-6	1.4420	59.66	156,841.4
	Nickel (Ni)	7440-02-0	0.9751	40.34	106,058.3
	Total		2.417		
Chip 0.55%	Silicon (Si)	7440-21-3	0.0362	72.55	3,937.4
	Gold (Au)	7440-57-5	0.0133	26.65	1,446.6
	Aluminum (Al)	7429-90-5	0.0004	0.80	43.5
	Total		0.050		
Bonding Wire 0.05%	Gold (Au)	7440-57-5	0.0049	100.00	533.0
	Total		0.005		
Molding 72.43%	Silica (SiO ₂)	14808-60-7	4.944	74.11	537,728.7
	Epoxy resin	29690-82-2	1.134	17.00	123,348.9
	Phenolic resin	9003-35-4	0.587	8.80	63,851.2
	Phosphorus(P)	7723-14-0	0.003	0.05	362.8
	Carbon Black	1333-86-4	0.003	0.04	290.2
	Total		6.671		
Plating 0.55%	Tin (Sn)	7440-31-5	0.05098	100.00	5,544.9
	Total		0.051		
	Total mass (mg)		9.19		

